Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.030”**

**.030”**

**CHIP BACK IS DRAIN**

**Top Material: Al**

**Backside Material: Ag**

**Bond Pad Size: .005” X .006”**

**Backside Potential: Drain**

**Mask Ref:**

**APPROVED BY: DK DIE SIZE .030” X .030” DATE: 8/25/21**

**MFG: ZETEX THICKNESS .010” P/N: ZVN4106**

**DG 10.1.2**Rev B, 7/19/02